NCE P-Channel Enhancement Mode Power MOSFET

Description

The NCE20P70G uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

V_{DS} =-20V,I_D =-70A

 $R_{DS(ON)}$ < 3m Ω @ V_{GS} =-4.5V

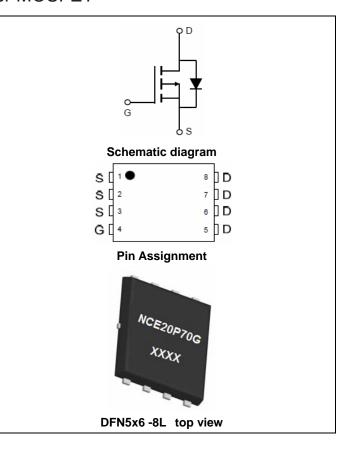
 $R_{DS(ON)} < 4m\Omega @ V_{GS} = -2.5V$

 $R_{DS(ON)}$ < 8m Ω @ V_{GS} =-1.8V

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation

Application

- Load switch
- Battery protection



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE20P70G	NCE20P70G	DFN 5x6 -8L	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-20	V
Gate-Source Voltage	V _G s	±10	V
Drain Current-Continuous	I _D	-70	А
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	-49.5	А
Pulsed Drain Current	I _{DM}	-280	А
Maximum Power Dissipation	P _D	130	W
Derating factor		0.64	W/°C
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}\!\mathbb{C}$

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	R _{θJC}	1.6	°C/W
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Electrical Characteristics (T_C=25 $^{\circ}$ C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics	·						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA -20		-	-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-20V,V _{GS} =0V -		-	1	μA	
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±10V,V _{DS} =0V	-	-	±100	nA	
On Characteristics (Note 3)			•				
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =-250μA	-0.4	-0.6	-1.0	V	
		V _{GS} =-4.5V, I _D =-20A	-	2.3	3	mΩ	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-2.5V, I _D =-20A	-	2.8	4		
		V _{GS} =-1.8V, I _D =-20A		3.8	8		
Forward Transconductance	g FS	V _{DS} =-5V,I _D =-20A	100	-	-	S	
Dynamic Characteristics (Note4)	•		•				
Input Capacitance	C _{lss})/ 40)/)/ 0)/	-	4950	-	PF	
Output Capacitance	Coss	V _{DS} =-10V,V _{GS} =0V,	-	380	-	PF	
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	290	-	PF	
Switching Characteristics (Note 4)			•				
Turn-on Delay Time	t _{d(on)}		-	20	-	nS	
Turn-on Rise Time	t _r	V_{DD} =-10V, R_{GEN} =3 Ω	-	50	-	nS	
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-4.5 V , R_L =0.5 Ω	-	100	-	nS	
Turn-Off Fall Time	t _f		-	40	-	nS	
Total Gate Charge	Qg)/ 40)/I 00A	-	100	-	nC	
Gate-Source Charge	Q _{gs}	V_{DS} =-10V, I_{D} =-20A, V_{GS} =-4.5V	-	21	-	nC	
Gate-Drain Charge	Q_{gd}	V _{GS} =-4.5V	-	32	-	nC	
Drain-Source Diode Characteristics	<u>.</u>						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-20A	-	-	-1.2	V	
Diode Forward Current (Note 2)	Is		-	-	-70	Α	
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF = -10A	-	48	-	nS	
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	55	-	nC	
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD				y LS+LD)	

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics (Curves)

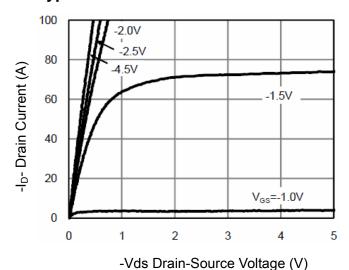


Figure 1 Output Characteristics

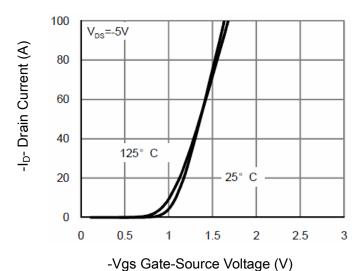


Figure 2 Transfer Characteristics

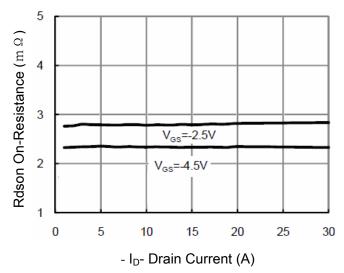


Figure 3 Rdson- Drain Current

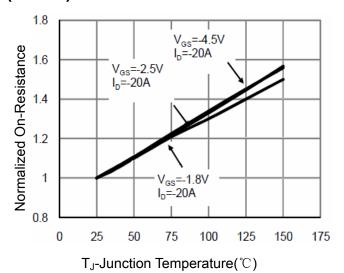


Figure 4 Rdson-Junction Temperature

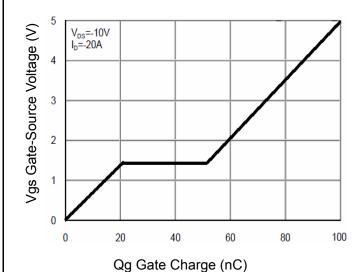


Figure 5 Gate Charge

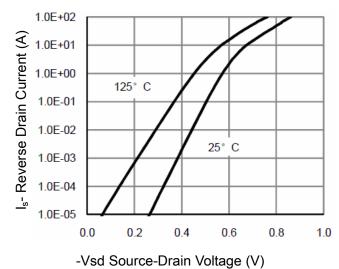


Figure 6 Source- Drain Diode Forward



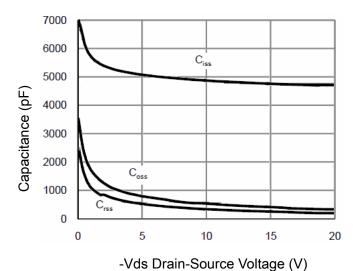
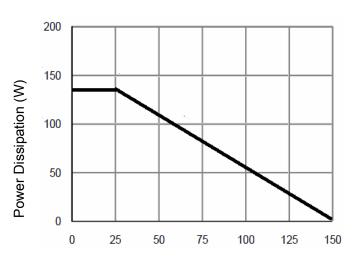


Figure 7 Capacitance vs Vds



 T_J -Junction Temperature(°C) Figure 9 Power De-rating

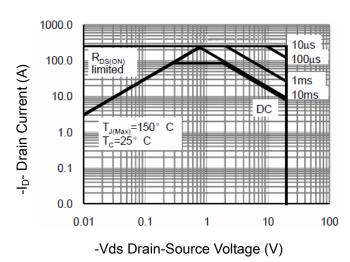


Figure 8 Safe Operation Area

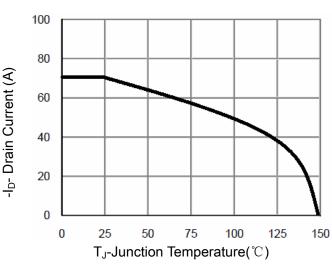


Figure 10 -Current De-rating

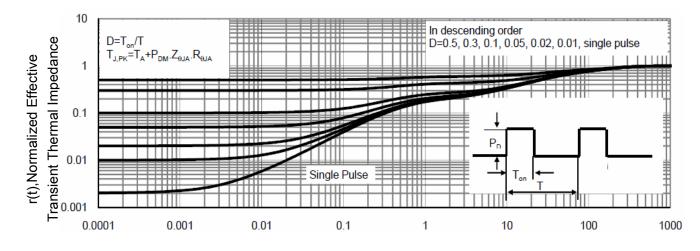
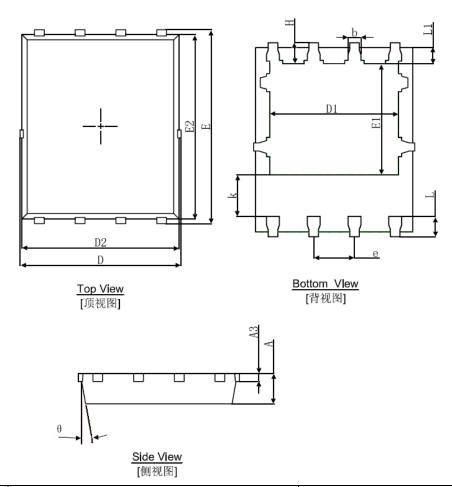


Figure 11 Normalized Maximum Transient Thermal Impedance

Square Wave Pluse Duration(sec)

DFN5X6-8L Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	0.900	1.000	0.035	0.039	
A3	0.25	54REF.	0.010REF.		
D	4.944	5.096	0.195	0.201	
E	5.974	6.126	0.235	0.241	
D1	3.910	4.110	0.154	0.162	
E1	3.375	3.575	0.133	0.141	
D2	4.824	4.976	0.190	0.196	
E2	5.674	5.826	0.223	0.229	
K	1.190	1.390	0.047	0.055	
b	0.035	0.450	0.014	0.018	
е	1.27	1.270(TYP.)		(TYP.)	
L	0.559	0.711	0.022	0.028	
L1	0.424	0.576	0.017	0.023	
Н	0.574	0.726	0.023	0.029	
θ	8°	12°	8°	12°	

NCE20P70G

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